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Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 08/14

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60191-4

March 2014

ICS 31.080

Supersedes EN 60191-4:1999 + A1:2002 + A2:2002

English version

**Mechanical standardization of semiconductor devices -
Part 4: Coding system and classification into forms of package outlines
for semiconductor device packages
(IEC 60191-4:2013)**

Normalisation mécanique des dispositifs à
semiconducteurs -
Partie 4: Système de codification et
classification en formes des boîtiers pour
dispositifs à semiconducteurs
(CEI 60191-4:2013)

Mechanische Normung von
Halbleiterbauelementen -
Teil 4: Codierungssystem für Gehäuse
und Eingruppierung der Gehäuse nach
der Gehäuseform für
Halbleiterbauelemente
(IEC 60191-4:2013)

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Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47D/837/FDIS, future edition 3 of IEC 60191-4, prepared by SC 47D, Semiconductor devices packaging, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-4:2014.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2014-09-21
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2016-11-14

This European Standard supersedes EN 60191-4:1999 and its Amendments A1:2002 and A2:2002.

EN 60191-4:2014 includes the following significant changes with respect to EN 60191-4:1999:

- a) Material code "S" is added to indicate a silicon based package.
- b) Description of "WL" is added to be used for general use.

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IEC 60191-4

Edition 3.0 2013-10

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Mechanical standardization of semiconductor devices –
Part 4: Coding system and classification into forms of package outlines for
semiconductor device packages**

**Normalisation mécanique des dispositifs à semiconducteurs –
Partie 4: Système de codification et classification en formes des structures des
boîtiers pour dispositifs à semiconducteurs**



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IEC 60191-4

Edition 3.0 2013-10

INTERNATIONAL STANDARD

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Part 4: Coding system and classification into forms of package outlines for
semiconductor device packages**

**Normalisation mécanique des dispositifs à semiconducteurs –
Partie 4: Système de codification et classification en formes des structures des
boîtiers pour dispositifs à semiconducteurs**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –**Part 4: Coding system and classification into forms of package
outlines for semiconductor device packages**

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International Standard IEC 60191-4 has been prepared by subcommittee 47D: Semiconductor devices packaging, of IEC technical committee 47: Semiconductor devices.

This third edition cancels and replaces the second edition published in 1999, Amendment 1:2001 and Amendment 2:2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) Material code "S" is added to indicate a silicon based package.
- b) Description of "WL" is added to be used for general use.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/837/FDIS	47D/848/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 60191 series, published under the general title *Mechanical standardization of semiconductor devices*, can be found on the IEC website.

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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 4: Coding system and classification into forms of package outlines for semiconductor device packages

1 Scope

This part of IEC 60191 specifies a method for the designation of package outlines and for the classification of forms of package outlines for semiconductor devices and a systematic method for generating universal descriptive designators for semiconductor device packages.

The descriptive designator provides a useful communication tool but has no implied control for assuring package interchangeability.

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